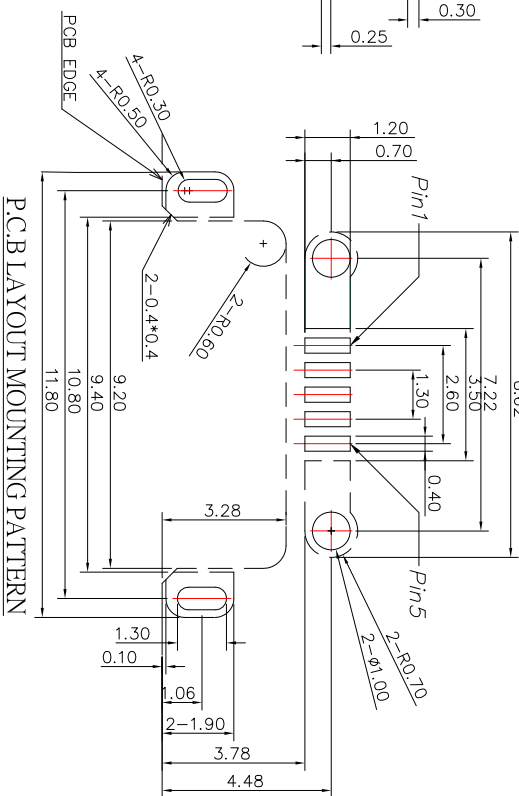
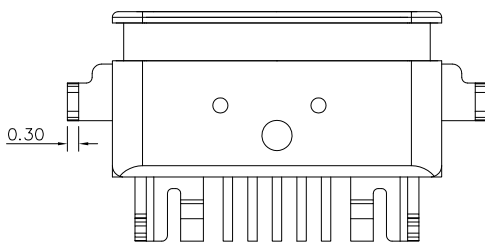
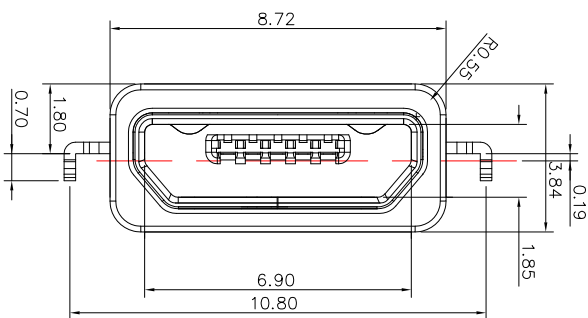
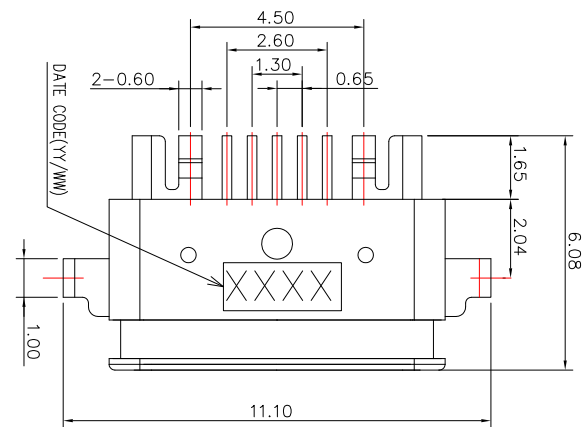


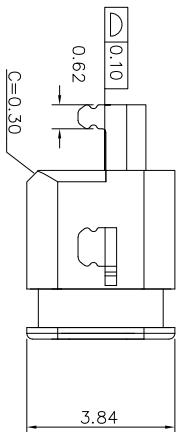
IP67



2UB-5B-WP13-x-S165

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"

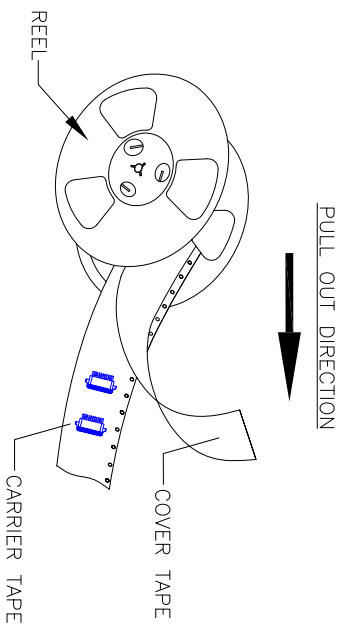
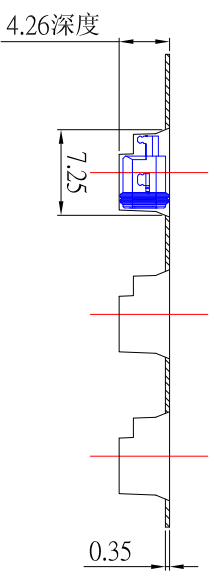
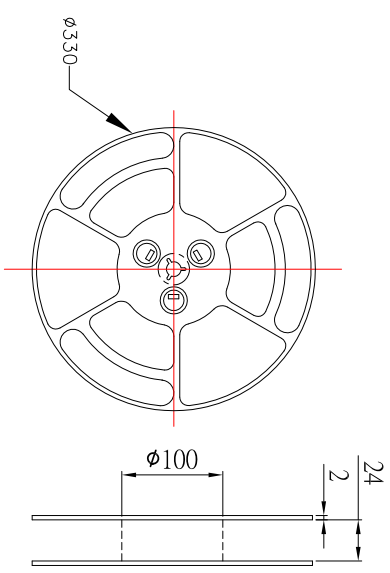
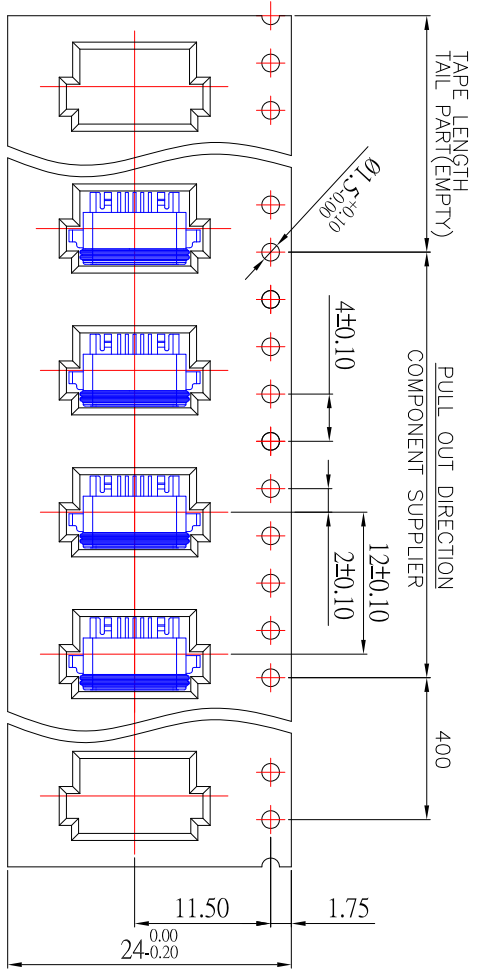


- NOTES:
- MATERIAL:
- 1.1 HOUSING: THERMOPLASTIC
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 SHELL: SUS
 - 1.4 O-RING: SILICON
- FINISH:
- 2.1 CONTACT: PLATED GOLD IN MATING AREA ; GOLD PLATED ON SOLDER BALLS ; UB-NICKEL UNDER PLATED OVERALL
 - 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER
- 3.SPECIFICATION:
- 3.1 RATING: 1.0A
 - 3.2 DIELECTRIC WITHSTANDING VOLTAGE: 500 VAC
 - 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
 - 3.4 INSULATION RESISTANCE: 1000 MΩ MIN.

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TITLE	MICRO USB SP+ B TYPE 沉板板上 H1.8 IP67		
DWN	Jack Lu	PART NO.	2UB-5B-WP13-x-S165
CHKD	Jacky Chen	SCALE	1:1
APVD	Tony Kao	SIZE	A3
		SHEET	1 OF 1
		REV	R2
		CUSTOMER COPY	

ITEM NO.	1	2	3	4	5	6	7	8
DESCRIPTION	新制尺寸	Jack	073118	3RD. ANGEL'S	UNIT'S	MM		
DRAWN	Jack	071718						
DATE	073118							
TOLERANCE UNLESS OTHERWISE STATED :	Up to 5 Above 5 ~ 15 Above 15 ~ 30 Above 30 ~ 50	±0.2 ±0.3 ±0.4 ±0.5 ±0.5						



TAPE & REEL PACKAGE:
 MATERIALS
 1.CARRIER TAPE: PS
 2.COVER TAPE: PET
 3.REEL: PS
 QUANTITY
 1.1300PCS PER REEL
 2.10 REEL PER CARTON(13000PCS PER CARTON)

ITEM NO.	1	2	DESCRIPTION	DRAWN	DATE	Up to 5	3RD. ANGEL'S	UNITS	MM
			新制電子	Jack	07318	±0.2			
			更新機架底座	Jack	07178	±0.3			
						±0.4			
						±0.3			
						±0.3			
						±0.3			
						±0.3			

Singatron Enterprise Co., Ltd.										
TITLE	MICRO USB SFP-B TYPE 沉板板上 H1.8 IP67									
DWN	Jack Lu	PART NO.	2UB-5B-WP13-x-S165							
CHKD	Jacky Chen	SCALE	1:1							
APVD	Tony Kao	SIZE	A3		SHEET	1 OF 1		REV	R2	
CUSTOMER COPY										